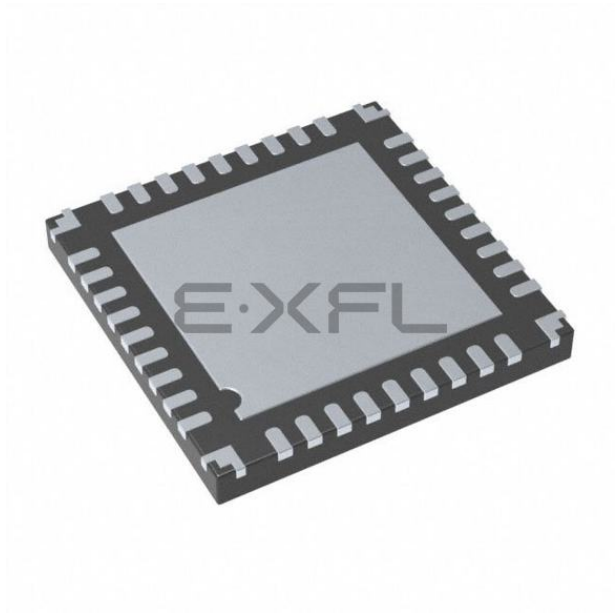

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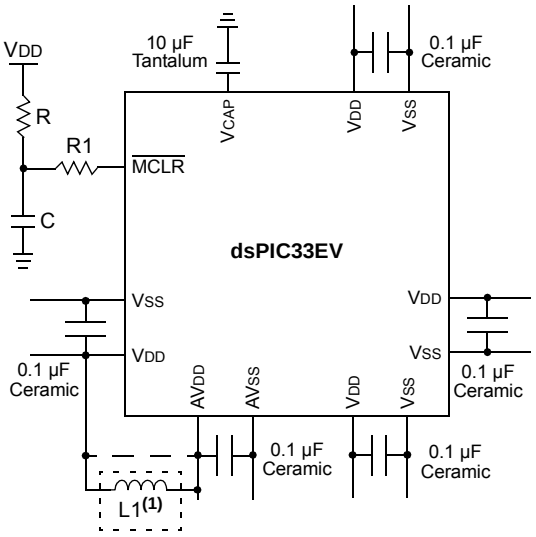
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	25
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 13x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	36-UFQFN Exposed Pad
Supplier Device Package	36-UQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev32gm103-e-m5

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 1Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{FCNV}{2} \quad \text{(i.e., ADC Conversion Rate/2)}$$

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

2.3 CPU Logic Filter Capacitor Connection (VCAP)

A low-ESR (<1 Ohms) capacitor is required on the VCAP pin, which is used to stabilize the internal voltage regulator output. The VCAP pin must not be connected to VDD, and must have a capacitor greater than 4.7 µF (10 µF is recommended), with at least a 16V rating connected to the ground. The type can be ceramic or tantalum. See **Section 30.0 "Electrical Characteristics"** for additional information.

The placement of this capacitor should be close to the VCAP pin. It is recommended that the trace length should not exceed one-quarter inch (6 mm).

2.4 Master Clear (MCLR) Pin

The MCLR pin provides two specific device functions:

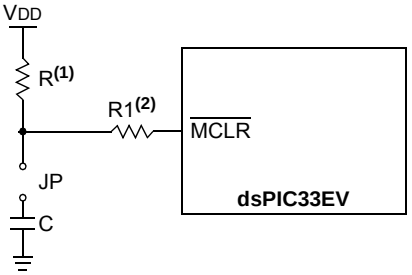
- Device Reset
- Device Programming and Debugging

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-1, it is recommended that the capacitor, C, be isolated from the MCLR pin during programming and debugging operations.

Place the components as shown in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the MCLR pin VIH and VIL specifications are met.

2: R1 ≤ 470Ω will limit any current flow into MCLR from the external capacitor, C, in the event of MCLR pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met.

REGISTER 3-1: SR: CPU STATUS REGISTER (CONTINUED)

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits(1,2)

111 = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

bit 4 **RA:** REPEAT Loop Active bit

1 = REPEAT loop is in progress
0 = REPEAT loop is not in progress

bit 3 **N:** MCU ALU Negative bit

1 = Result was negative
0 = Result was non-negative (zero or positive)

bit 2 **OV:** MCU ALU Overflow bit

This bit is used for signed arithmetic (2's complement). It indicates an overflow of the magnitude that causes the sign bit to change state.
1 = Overflow occurred for signed arithmetic (in this arithmetic operation)
0 = Overflow has not occurred for signed arithmetic

bit 1 **Z:** MCU ALU Zero bit

1 = An operation that affects the Z bit has set it at some time in the past
0 = The most recent operation that affects the Z bit has cleared it (i.e., a non-zero result)

bit 0 **C:** MCU ALU Carry/$\overline{\text{Borrow}}$ bit

1 = A carry-out from the Most Significant bit (MSb) of the result occurred
0 = No carry-out from the Most Significant bit of the result occurred

Note 1: The IPL<2:0> bits are concatenated with the IPL3 bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL if IPL3 = 1. User interrupts are disabled when IPL3 = 1.

2: The IPL<2:0> Status bits are read-only when the NSTDIS bit (INTCON1<15>) = 1.

3: A data write to the SR register can modify the SA and SB bits by either a data write to SA and SB or by clearing the SAB bit. To avoid a possible SA or SB bit write race condition, the SA and SB bits should not be modified using the bit operations.

REGISTER 8-7: DMAxPAD: DMA CHANNEL x PERIPHERAL ADDRESS REGISTER(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PAD<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PAD<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **PAD<15:0>:** DMA Peripheral Address Register bits

Note 1: If the channel is enabled (i.e., active), writes to this register may result in unpredictable behavior of the DMA channel and should be avoided.

REGISTER 8-8: DMAxCNT: DMA CHANNEL x TRANSFER COUNT REGISTER(1)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	CNT<13:8>(2)					
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CNT<7:0>(2)							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-0 **CNT<13:0>:** DMA Transfer Count Register bits(2)

Note 1: If the channel is enabled (i.e., active), writes to this register may result in unpredictable behavior of the DMA channel and should be avoided.

2: The number of DMA transfers = CNT<13:0> + 1.

REGISTER 8-12: DMARQC: DMA REQUEST COLLISION STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	RQCOL3	RQCOL2	RQCOL1	RQCOL0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-4 **Unimplemented:** Read as ‘0’

bit 3 **RQCOL3:** Channel 3 Transfer Request Collision Flag bit
1 = User force and interrupt-based request collision is detected
0 = User force and interrupt-based request collision is not detected

bit 2 **RQCOL2:** Channel 2 Transfer Request Collision Flag bit
1 = User force and interrupt-based request collision is detected
0 = User force and interrupt-based request collision is not detected

bit 1 **RQCOL1:** Channel 1 Transfer Request Collision Flag bit
1 = User force and interrupt-based request collision is detected
0 = User force and interrupt-based request collision is not detected

bit 0 **RQCOL0:** Channel 0 Transfer Request Collision Flag bit
1 = User force and interrupt-based request collision is detected
0 = User force and interrupt-based request collision is not detected

13.0 TIMER2/3 AND TIMER4/5

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Timers"** (DS70362) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

These modules are 32-bit timers, which can also be configured as four independent, 16-bit timers with selectable operating modes.

As a 32-bit timer, Timer2/3 and Timer4/5 operate in the following three modes:

- Two Independent 16-Bit Timers (e.g., Timer2 and Timer3) with all 16-Bit Operating modes (except Asynchronous Counter mode)
- Single 32-Bit Timer
- Single 32-Bit Synchronous Counter

They also support these features:

- Timer Gate Operation
- Selectable Prescaler Settings
- Timer Operation during Idle and Sleep modes
- Interrupt on a 32-Bit Period Register Match
- Time Base for Input Capture and Output Compare Modules
- ADC1 Event Trigger (Timer2/3 only)

Individually, all four of the 16-bit timers can function as synchronous timers or counters. They also offer the features listed previously, except for the event trigger; this is implemented only with Timer2/3. The operating modes and enabled features are determined by setting the appropriate bit(s) in the T2CON, T3CON, T4CON and T5CON registers. T2CON and T4CON are shown in generic form in Register 13-1. The T3CON and T5CON registers are shown in Register 13-2.

For 32-bit timer/counter operation, Timer2 and Timer4 are the least significant word (lsw). Timer3 and Timer5 are the most significant word (msw) of the 32-bit timers.

Note: For 32-bit operation, the T3CON and T5CON control bits are ignored. Only the T2CON and T4CON control bits are used for setup and control. Timer2 and Timer4 clock and gate inputs are utilized for the 32-bit timer modules, but an interrupt is generated with the Timer3 and Timer5 interrupt flags.

Block diagrams for the Type B and Type C timers are shown in Figure 13-1 and Figure 13-2, respectively.

A block diagram for an example 32-bit timer pair (Timer2/3 and Timer4/5) is shown in Figure 13-3.

Note: Only Timer2, Timer3, Timer4 and Timer5 can trigger a DMA data transfer.

20.3 Receive Mode

The module can be configured for receive operation by setting the RCVEN (SENTxCON1<11>) bit. The time between each falling edge is compared to SYNCMIN<15:0> (SENTxCON3<15:0>) and SYNCMAX<15:0> (SENTxCON2<15:0>), and if the measured time lies between the minimum and maximum limits, the module begins to receive data. The validated Sync time is captured in the SENTxSYNC register and the tick time is calculated. Subsequent falling edges are verified to be within the valid data width and the data is stored in the SENTxDATH/L register. An interrupt event is generated at the completion of the message and the user software should read the SENTx Data register before the reception of the next nibble. The equation for SYNCMIN<15:0> and SYNCMAX<15:0> is shown in Equation 20-3.

EQUATION 20-3: SYNCMIN<15:0> AND SYNCMAX<15:0> CALCULATIONS

$$T_{TICK} = T_{CLK} \bullet (TICKTIME\langle 15{:}0\rangle + 1)$$

$$FRAMETIME\langle 15{:}0\rangle = T_{TICK}/T_{FRAME}$$

$$SyncCount = 8 \times F_{RCV} \times T_{TICK}$$

$$SYNCMIN\langle 15{:}0\rangle = 0.8 \times SyncCount$$

$$SYNCMAX\langle 15{:}0\rangle = 1.2 \times SyncCount$$

$$FRAMETIME\langle 15{:}0\rangle \geq 122 + 27N$$

$$FRAMETIME\langle 15{:}0\rangle \geq 848 + 12N$$

Where:
T_{FRAME} = Total time of the message from ms
N = The number of data nibbles in message, 1-6
F_{RCV} = FCY x prescaler
T_{CLK} = FCY/Prescaler

For TTICK = 3.0 µs and FCLK = 4 MHz, SYNCMIN<15:0> = 76.

Note: To ensure a Sync period can be identified, the value written to SYNCMIN<15:0> must be less than the value written to SYNCMAX<15:0>.

20.3.1 RECEIVE MODE CONFIGURATION

20.3.1.1 Initializing the SENTx Module:

Perform the following steps to initialize the module:

1. Write RCVEN (SENTxCON1<11>) = 1 for Receive mode.
2. Write NIBCNT<2:0> (SENTxCON1<2:0>) for the desired data frame length.
3. Write CRCEN (SENTxCON1<8>) for hardware or software CRC validation.
4. Write PPP (SENTxCON1<7>) = 1 if pause pulse is present.
5. Write SENTxCON2 with the value of SYNCMAXx (Nominal Sync Period + 20%).
6. Write SENTxCON3 with the value of SYNCMINx (Nominal Sync Period – 20%).
7. Enable interrupts and set interrupt priority.
8. Set the SNTEN (SENTxCON1<15>) bit to enable the module.

The data should be read from the SENTxDATH/L register after the completion of the CRC and before the next message frame's status nibble. The recommended method is to use the message frame completion interrupt trigger.

REGISTER 22-10: CxCFG2: CANx BAUD RATE CONFIGURATION REGISTER 2

U-0	R/W-x	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	WAKFIL	—	—	—	SEG2PH2	SEG2PH1	SEG2PH0
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SEG2PHTS	SAM	SEG1PH2	SEG1PH1	SEG1PH0	PRSEG2	PRSEG1	PRSEG0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14 **WAKFIL:** Select CAN Bus Line Filter for Wake-up bit
1 = Uses CAN bus line filter for wake-up
0 = CAN bus line filter is not used for wake-up

bit 13-11 **Unimplemented:** Read as '0'

bit 10-8 **SEG2PH<2:0>:** Phase Segment 2 bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

bit 7 **SEG2PHTS:** Phase Segment 2 Time Select bit
1 = Freely programmable
0 = Maximum of SEG1PH<2:0> bits or Information Processing Time (IPT), whichever is greater

bit 6 **SAM:** Sample of the CAN Bus Line bit
1 = Bus line is sampled three times at the sample point
0 = Bus line is sampled once at the sample point

bit 5-3 **SEG1PH<2:0>:** Phase Segment 1 bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

bit 2-0 **PRSEG<2:0>:** Propagation Time Segment bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

REGISTER 22-13: CxBUFPNT2: CANx FILTERS 4-7 BUFFER POINTER REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F7BP3	F7BP2	F7BP1	F7BP0	F6BP3	F6BP2	F6BP1	F6BP0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F5BP3	F5BP2	F5BP1	F5BP0	F4BP3	F4BP2	F4BP1	F4BP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **F7BP<3:0>:** RX Buffer Mask for Filter 7 bits
1111 = Filter hits received in RX FIFO buffer
1110 = Filter hits received in RX Buffer 14
•
•
•
0001 = Filter hits received in RX Buffer 1
0000 = Filter hits received in RX Buffer 0

bit 11-8 **F6BP<3:0>:** RX Buffer Mask for Filter 6 bits (same values as bits 15-12)

bit 7-4 **F5BP<3:0>:** RX Buffer Mask for Filter 5 bits (same values as bits 15-12)

bit 3-0 **F4BP<3:0>:** RX Buffer Mask for Filter 4 bits (same values as bits 15-12)

REGISTER 22-15: CxBUFPNT4: CANx FILTERS 12-15 BUFFER POINTER REGISTER 4

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F15BP3	F15BP2	F15BP1	F15BP0	F14BP3	F14BP2	F14BP1	F14BP0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F13BP3	F13BP2	F13BP1	F13BP0	F12BP3	F12BP2	F12BP1	F12BP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **F15BP<3:0>:** RX Buffer Mask for Filter 15 bits
1111 = Filter hits received in RX FIFO buffer
1110 = Filter hits received in RX Buffer 14
•
•
•
0001 = Filter hits received in RX Buffer 1
0000 = Filter hits received in RX Buffer 0

bit 11-8 **F14BP<3:0>:** RX Buffer Mask for Filter 14 bits (same values as bits 15-12)

bit 7-4 **F13BP<3:0>:** RX Buffer Mask for Filter 13 bits (same values as bits 15-12)

bit 3-0 **F12BP<3:0>:** RX Buffer Mask for Filter 12 bits (same values as bits 15-12)

REGISTER 23-2: CTMUCON2: CTMU CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
EDG1MOD	EDG1POL	EDG1SEL3	EDG1SEL2	EDG1SEL1	EDG1SEL0	EDG2STAT	EDG1STAT
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
EDG2MOD	EDG2POL	EDG2SEL3	EDG2SEL2	EDG2SEL1	EDG2SEL0	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **EDG1MOD:** Edge 1 Edge Sampling Mode Selection bit
1 = Edge 1 is edge-sensitive
0 = Edge 1 is level-sensitive

bit 14 **EDG1POL:** Edge 1 Polarity Select bit
1 = Edge 1 is programmed for a positive edge response
0 = Edge 1 is programmed for a negative edge response

bit 13-10 **EDG1SEL<3:0>:** Edge 1 Source Select bits
1111 = FOSC
1110 = OSCI pin
1101 = FRC Oscillator
1100 = BFRC Oscillator
1011 = Internal LPRC Oscillator
1010 = Reserved
1001 = Reserved
1000 = Reserved
0111 = Reserved
0110 = Reserved
0101 = Reserved
0100 = Reserved
0011 = CTED1 pin
0010 = CTED2 pin
0001 = OC1 module
0000 = TMR1 module

bit 9 **EDG2STAT:** Edge 2 Status bit
Indicates the status of Edge 2 and can be written to control the edge source.
1 = Edge 2 has occurred
0 = Edge 2 has not occurred

bit 8 **EDG1STAT:** Edge 1 Status bit
Indicates the status of Edge 1 and can be written to control the edge source.
1 = Edge 1 has occurred
0 = Edge 1 has not occurred

bit 7 **EDG2MOD:** Edge 2 Edge Sampling Mode Selection bit
1 = Edge 2 is edge-sensitive
0 = Edge 2 is level-sensitive

bit 6 **EDG2POL:** Edge 2 Polarity Select bit
1 = Edge 2 is programmed for a positive edge response
0 = Edge 2 is programmed for a negative edge response

REGISTER 25-2: CMxCON: COMPARATOR x CONTROL REGISTER (x = 1, 2, 3 OR 5)

R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R-0
CON	COE	CPOL	—	—	OPAEN(2)	CEVT	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1(3)	EVPOL0(3)	—	CREF(1)	—	—	CCH1(1)	CCH0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CON:** Op Amp/Comparator x Enable bit
1 = Op Amp/Comparator x is enabled
0 = Op Amp/Comparator x is disabled

bit 14 **COE:** Comparator x Output Enable bit
1 = Comparator output is present on the CxOUT pin
0 = Comparator output is internal only

bit 13 **CPOL:** Comparator x Output Polarity Select bit
1 = Comparator output is inverted
0 = Comparator output is not inverted

bit 12-11 **Unimplemented:** Read as '0'

bit 10 **OPAEN:** Op Amp x Enable bit(2)
1 = Op Amp x is enabled
0 = Op Amp x is disabled

bit 9 **CEVT:** Comparator x Event bit
1 = Comparator event, according to EVPOL<1:0> settings, occurred; disables future triggers and interrupts until the bit is cleared
0 = Comparator event did not occur

bit 8 **COUT:** Comparator x Output bit
When CPOL = 0 (non-inverted polarity):
1 = VIN+ > VIN-
0 = VIN+ < VIN-
When CPOL = 1 (inverted polarity):
1 = VIN+ < VIN-
0 = VIN+ > VIN-

Note 1: Inputs that are selected and not available will be tied to VSS. See the **"Pin Diagrams"** section for available inputs for each package.

2: The op amp and the comparator can be used simultaneously in these devices. The OPAEN bit only enables the op amp while the comparator is still functional.

3: After configuring the comparator, either for a high-to-low or low-to-high COUT transition (EVPOL<1:0> (CMxCON<7:6>) = 10 or 01), the Comparator x Event bit, CEVT (CMxCON<9>), and the Comparator Interrupt Flag, CMPIF (IFS1<2>), must be cleared before enabling the Comparator Interrupt Enable bit, CMPIE (IEC1<2>).

TABLE 30-7: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typ.(2)**	**Max.**	**Units**	**Conditions**		
Idle Current (IIDLE)(1)						
DC40d	1.25	2	mA	-40°C	5.0V	10 MIPS
DC40a	1.25	2	mA	+25°C		
DC40b	1.5	2.6	mA	+85°C		
DC40c	1.5	2.6	mA	+125°C		
DC42d	2.3	3	mA	-40°C	5.0V	20 MIPS
DC42a	2.3	3	mA	+25°C		
DC42b	2.6	3.45	mA	+85°C		
DC42c	2.6	3.85	mA	+125°C		
DC44d	6.9	8	mA	-40°C	5.0V	70 MIPS
DC44a	6.9	8	mA	+25°C		
DC44b	7.25	8.6	mA	+85°C		

Note 1: Base Idle current (IIDLE) is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as outputs and driving low
- $\overline{MCLR}$ = VDD, WDT and FSCM are disabled
- No peripheral modules are operating or being clocked (defined PMDx bits are all ones)
- The NVMSIDL bit (NVMCON<12>) = 1 (i.e., Flash regulator is set to standby while the device is in Idle mode)
- The VREGSF bit (RCON<11>) = 0 (i.e., Flash regulator is set to standby while the device is in Sleep mode)

2: Data in “Typ.” column is at 5.0V, +25°C unless otherwise stated.

30.2 AC Characteristics and Timing Parameters

This section defines the dsPIC33EVXXXGM00X/10X family AC characteristics and timing parameters.

TABLE 30-15: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended Operating voltage VDD range as described in **Section 30.1 "DC Characteristics"**.

FIGURE 30-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

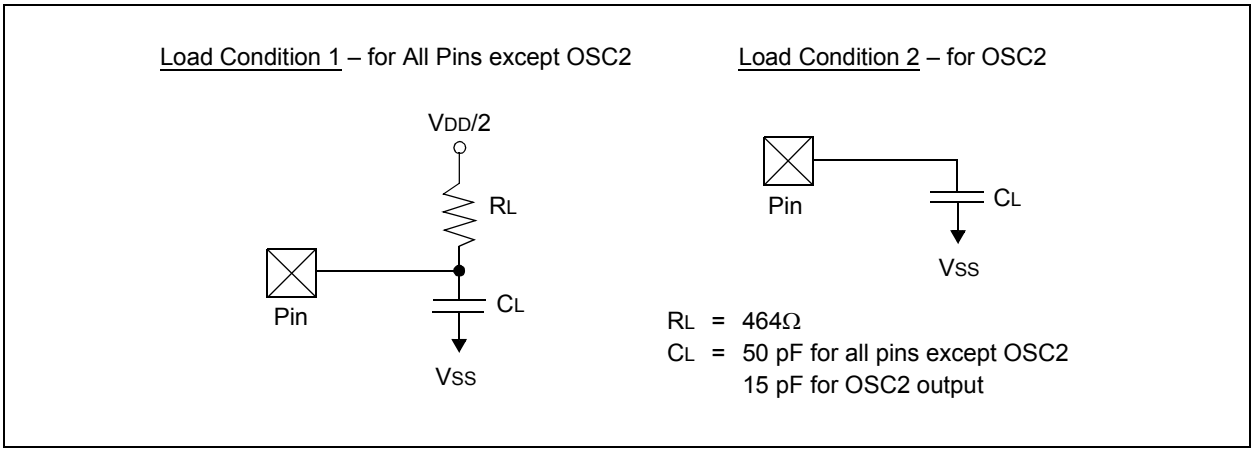


TABLE 30-16: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
DO50	COSCO	OSC2 Pin	—	—	15	pF	In XT and HS modes, when external clock is used to drive OSC1
DO56	CIO	All I/O Pins and OSC2	—	—	50	pF	EC mode
DO58	CB	SCLx, SDAx	—	—	400	pF	In I^2C mode

TABLE 30-34: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	15	MHz	See **Note 3**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS2}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS2}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	See **Note 4**
SP52	TscH2ssH TscL2ssH	$\overline{SS2}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	See **Note 4**
SP60	TssL2doV	$\overline{SDO2}$ Data Output Valid after $\overline{SS2}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ." column is at 5.0V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 66.7 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

FIGURE 30-18: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING CHARACTERISTICS

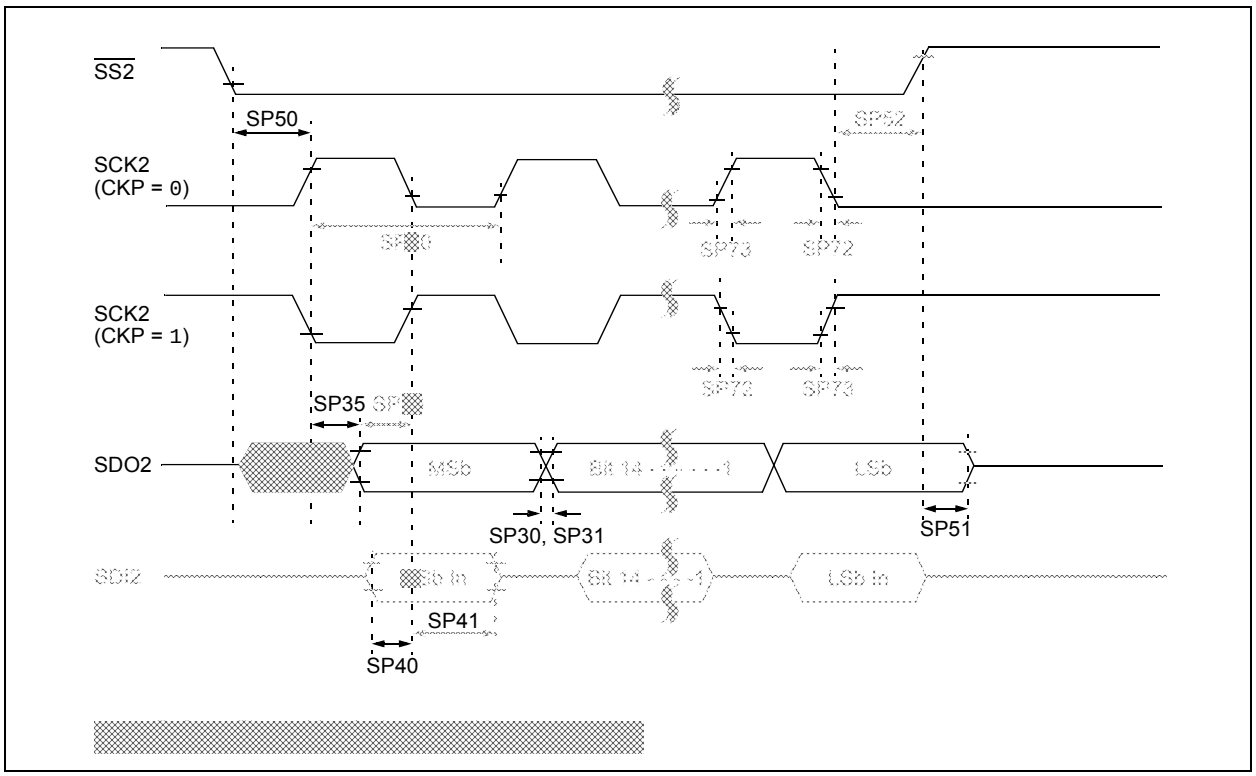
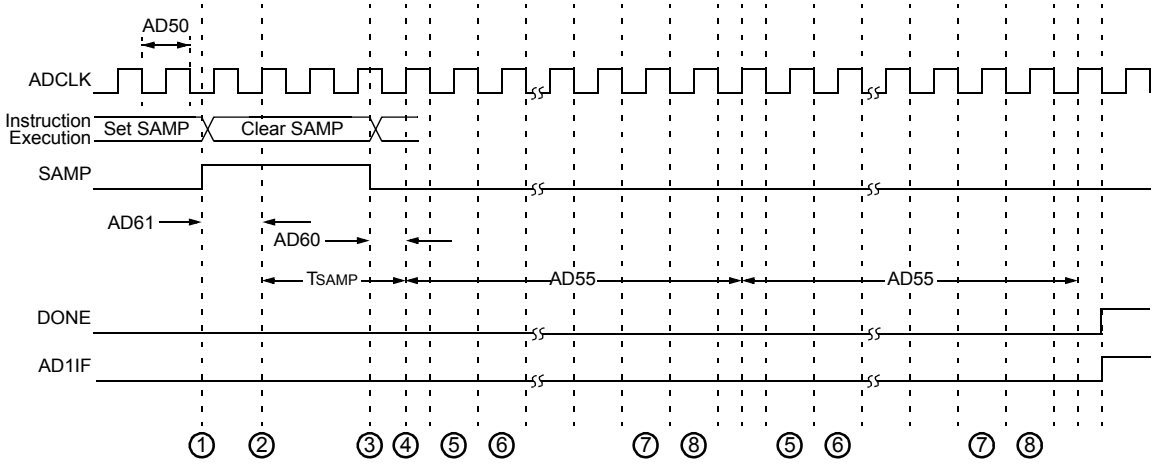


TABLE 30-54: ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions (see Note 1): 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
Device Supply							
AD01	AVDD	Module VDD Supply	Greater of: VDD – 0.3 or VBOR	—	Lesser of: VDD + 0.3 or 5.5	V	
AD02	AVSS	Module VSS Supply	VSS – 0.3	—	VSS + 0.3	V	
Reference Inputs							
AD05	VREFH	Reference Voltage High	4.5	—	5.5	V	VREFH = AVDD, VREFL = AVSS = 0
AD06	VREFL	Reference Voltage Low	AVSS	—	AVDD – VBORMIN	V	See **Note 1**
AD06a			0	—	0	V	VREFH = AVDD, VREFL = AVSS = 0
AD07	VREF	Absolute Reference Voltage	4.5	—	5.5	V	VREF = VREFH – VREFL
AD08	IREF	Current Drain	— —	— —	10 600	μA μA	ADC off ADC on
AD09	IAD	Operating Current	— —	5 2	— —	mA mA	ADC operating in 10-bit mode (see **Note 1**) ADC operating in 12-bit mode (see **Note 1**)
Analog Input							
AD12	VINH	Input Voltage Range VINH	VINL	—	VREFH	V	This voltage reflects Sample-and-Hold Channels 0, 1, 2 and 3 (CH0-CH3), positive input
AD13	VINL	Input Voltage Range VINL	VREFL	—	AVSS + 1V	V	This voltage reflects Sample-and-Hold Channels 0, 1, 2 and 3 (CH0-CH3), negative input
AD17	RIN	Recommended Impedance of Analog Voltage Source	—	—	200	Ω	Impedance to achieve maximum performance of ADC

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but is not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Refer to Parameter BO10 in Table 30-12 for the minimum and maximum BOR values.

FIGURE 30-35: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000, SSRCG = 0)



① – Software sets ADxCON1. SAMP to start sampling.

② – Sampling starts after discharge period. TSAMP is described in **"Analog-to-Digital Converter (ADC)"** (DS70621) of the *"dsPIC33/PIC24 Family Reference Manual"*.

③ – Software clears ADxCON1. SAMP to start conversion.

④ – Sampling ends, conversion sequence starts.

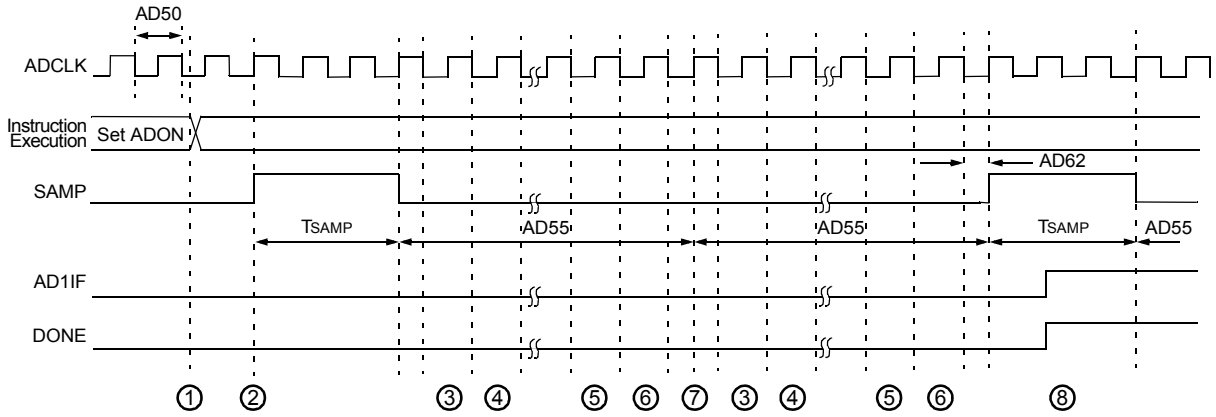
⑤ – Convert bit 9.

⑥ – Convert bit 8.

⑦ – Convert bit 0.

⑧ – One TAD for end of conversion.

FIGURE 30-36: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SSRCG = 0, SAMC<4:0> = 00010)



① – Software sets ADxCON1. ADON to start ADC operation.

② – Sampling starts after discharge period. TSAMP is described in **"Analog-to-Digital Converter (ADC)"** (DS70621) of the *"dsPIC33/PIC24 Family Reference Manual"*.

③ – Convert bit 9.

④ – Convert bit 8.

⑤ – Convert bit 0.

⑥ – One TAD for end of conversion.

⑦ – Begin conversion of next channel.

⑧ – Sample for time specified by SAMC<4:0>.

TABLE 31-19: ADC MODULE SPECIFICATIONS (10-BIT MODE)

AC CHARACTERISTICS			Standard Operating Conditions (see Note 1): 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
ADC Accuracy (10-Bit Mode)							
HAD20b	Nr	Resolution	10 data bits			bits	
HAD21b	INL	Integral Nonlinearity	-1.5	—	+1.5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5.5V
HAD22b	DNL	Differential Nonlinearity	≥ 1	—	< 1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5.5V
HAD23b	GERR	Gain Error	1	3	6	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5.5V
HAD24b	EOFF	Offset Error	1	2	4	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5.5V

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but is not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Refer to Parameter HBO10 in Table 31-10 for the minimum and maximum BOR values.

FIGURE 33-7: TYPICAL IIDLE vs. VDD (EC MODE, 20 MIPS)

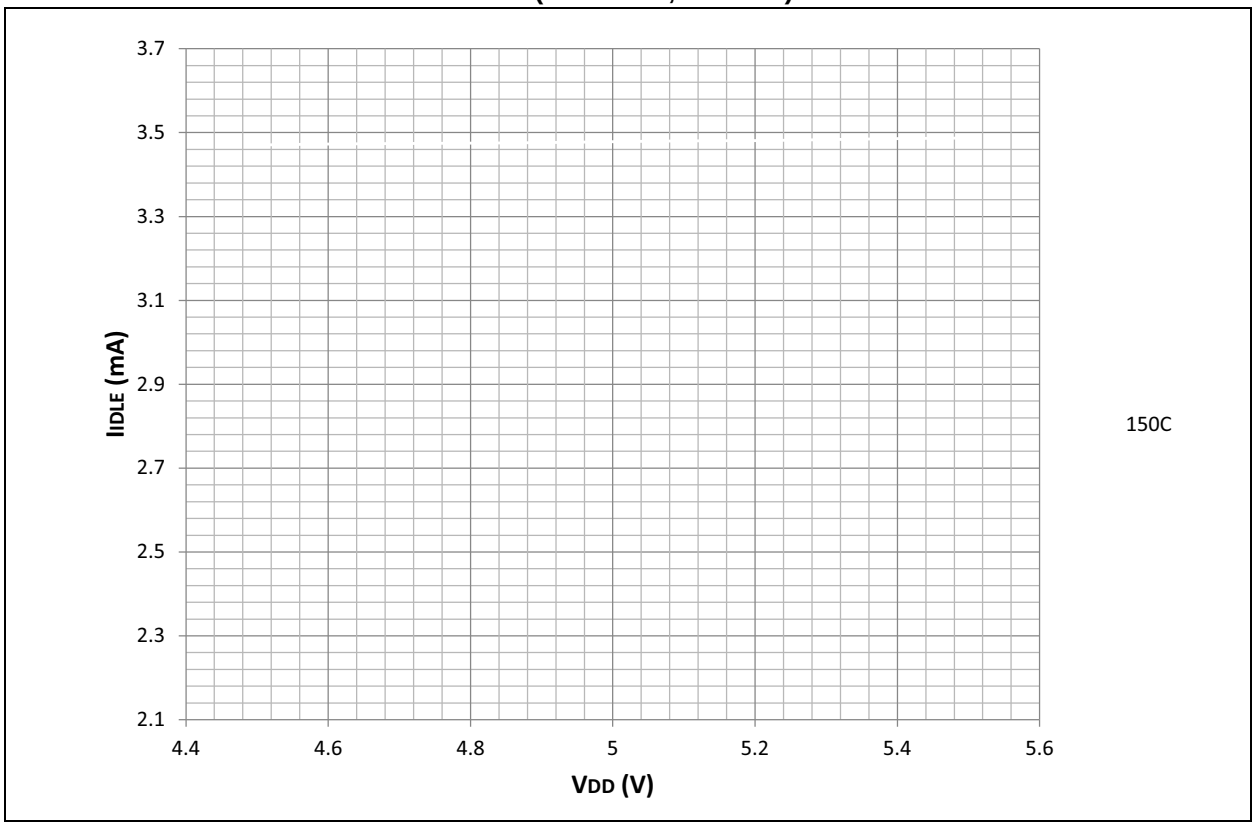


FIGURE 33-8: TYPICAL IIDLE vs. VDD (EC MODE, 40 MIPS)